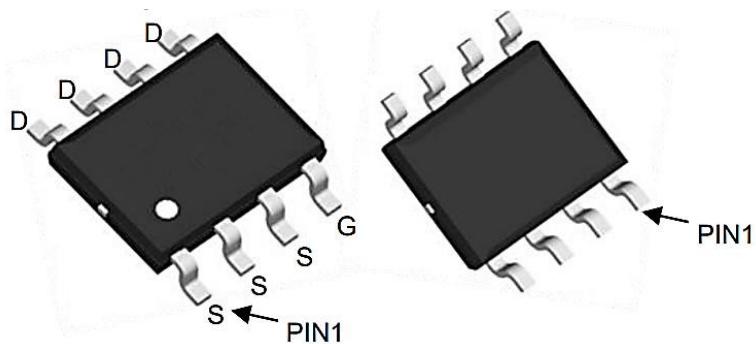
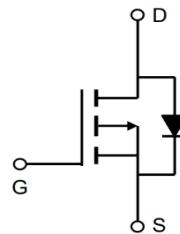


**-30V P-Channel Enhancement Mode MOSFET**
**Description**

The AP20P03S uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.


**General Features**

$V_{DS} = -30V$   $I_D = -20A$

$R_{DS(ON)} < 7.5m\Omega$  @  $V_{GS} = -10V$  (Type: 5.2m $\Omega$ )

**Application**

Lithium battery protection

Wireless impact

Mobile phone fast charging

**Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
AP20P03S	SOP-8L	AP20P03S XXX YYYY	3000

**Absolute Maximum Ratings (TC=25°C unless otherwise noted)**

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-30	V
VGS	Gate-Source Voltage	$\pm 20$	V
ID@TC=25°C	Continuous Drain Current, VGS @ -10V1	-20	A
ID@TC=100°C	Continuous Drain Current, VGS @ -10V1	-16.8	A
IDM	Pulsed Drain Current2	-60	A
EAS	Single Pulse Avalanche Energy3	125	mJ
PD@TC=25°C	Total Power Dissipation4	69	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient 1	85	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case1	1.6	°C/W

**-30V P-Channel Enhancement Mode MOSFET**
**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-30	-34	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $I_{\text{D}}=-1\text{mA}$	---	-0.0232	---	$\text{V}/^{\circ}\text{C}$
$\text{RDS}(\text{ON})$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-20\text{A}$	---	5.2	7.5	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-15\text{A}$	---	8.0	11	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1.2	-1.4	-2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	4.6	---	$\text{mV}/^{\circ}\text{C}$
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^{\circ}\text{C}$	---	---	-1	$\text{uA}$
		$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^{\circ}\text{C}$	---	---	-5	
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$\text{gfs}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_{\text{D}}=-30\text{A}$	---	30	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	9.8	---	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ $I_{\text{D}}=-20\text{A}$	---	35	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	9.9	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	10.5	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-15\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=3.0\Omega$ $I_{\text{D}}=-20\text{A}$	---	10.8	---	$\text{ns}$
$T_r$	Rise Time		---	13.2	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	73	---	
$T_f$	Fall Time		---	35	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3520	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	465	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	370	---	
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-70	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	-130	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{s}}=-1\text{A}$ , $T_J=25^{\circ}\text{C}$	---	---	-1.3	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=-20\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^{\circ}\text{C}$	---	25	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	10	---	nC

**Note :**

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The power dissipation is limited by  $175^{\circ}\text{C}$  junction temperature
- 4、EAS condition:  $T_J=25^{\circ}\text{C}$ ,  $V_{\text{DD}}= -24\text{V}$ ,  $V_{\text{G}}= -10\text{V}$ ,  $R_G=7\Omega$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}= -40\text{A}$
- 5、The data is theoretically the same as  $\text{ID}$  and  $\text{IDM}$  , in real applications , should be limited by total power dissipation.

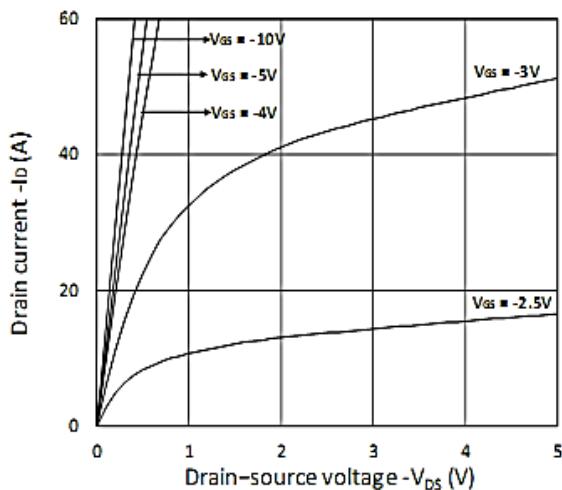
**-30V P-Channel Enhancement Mode MOSFET**
**Typical Characteristics**


Figure 1. Output Characteristics

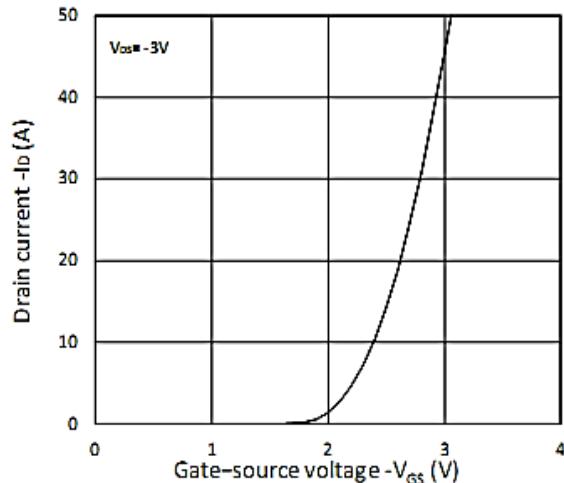


Figure 2. Transfer Characteristics

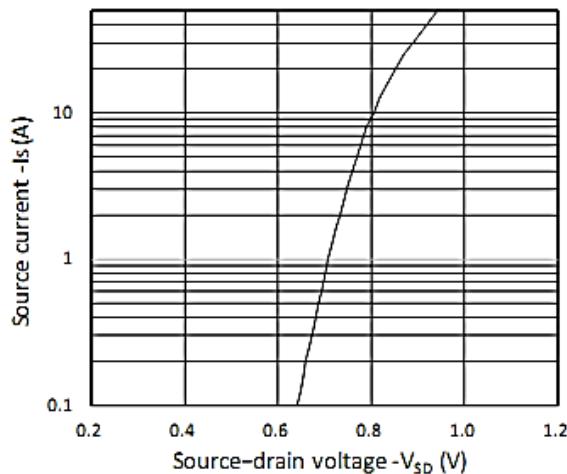
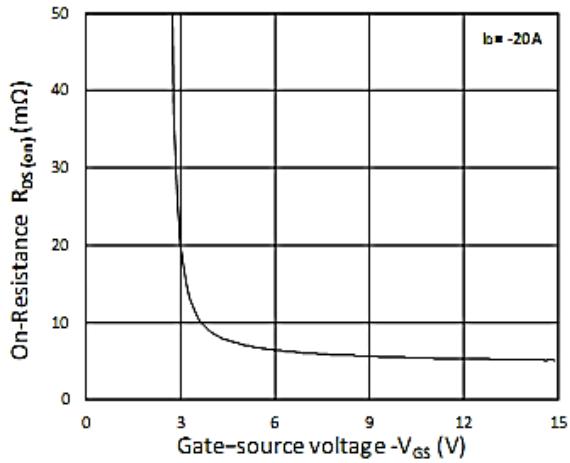
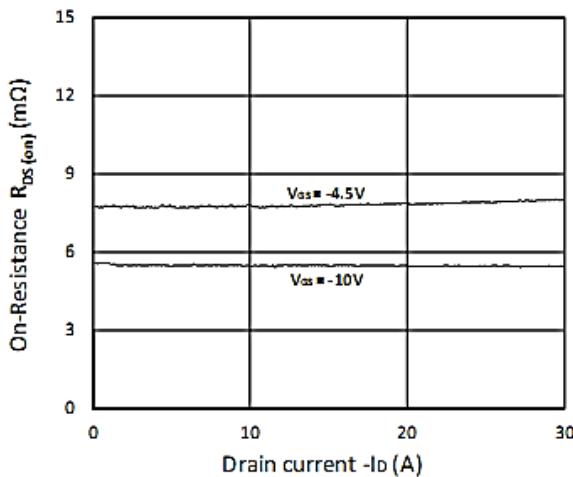
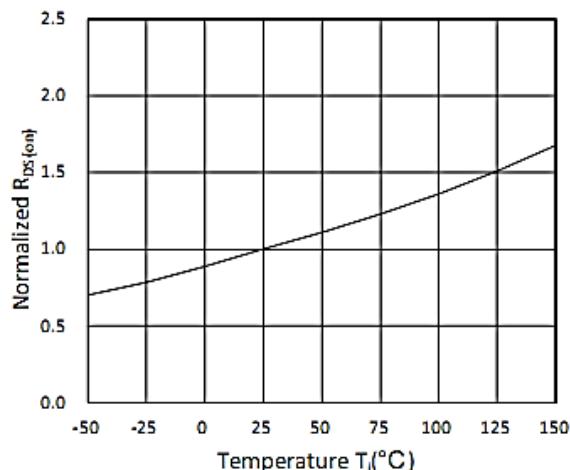


Figure 3. Forward Characteristics of Reverse


Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$ 

Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ 

Figure 6. Normalized  $R_{DS(ON)}$  vs. Temperature

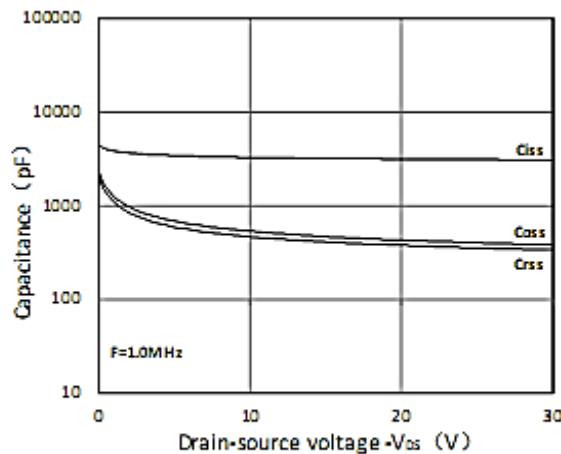

**-30V P-Channel Enhancement Mode MOSFET**


Figure 7. Capacitance Characteristics

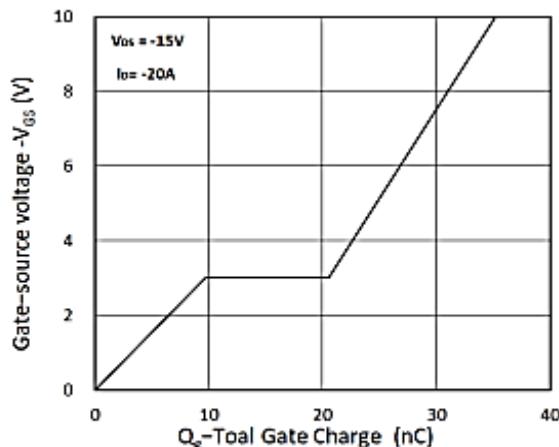


Figure 8. Gate Charge Characteristics

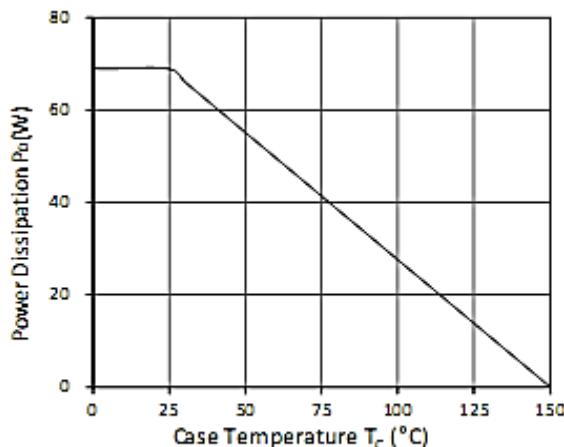


Figure 9. Power Dissipation

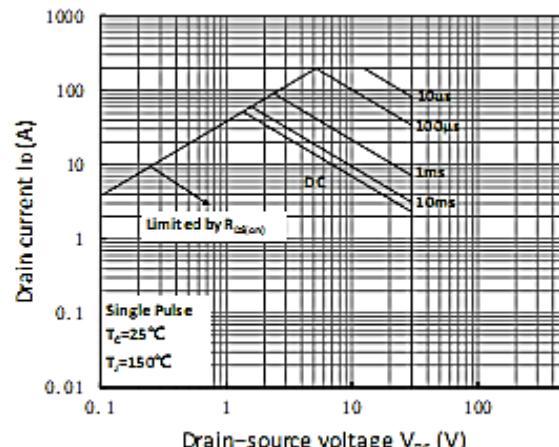


Figure 10. Safe Operating Area

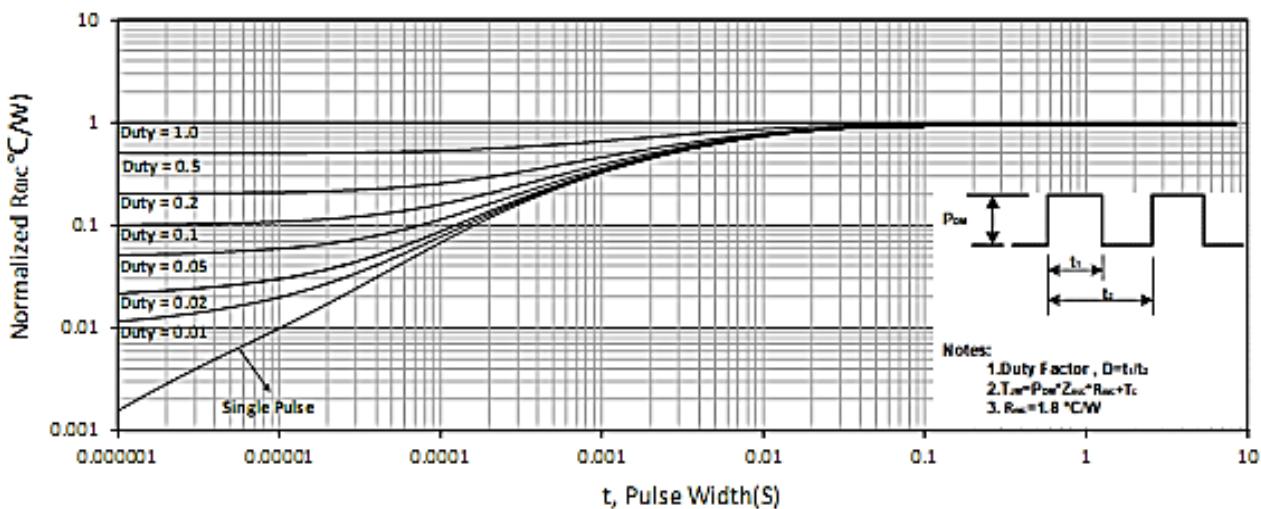
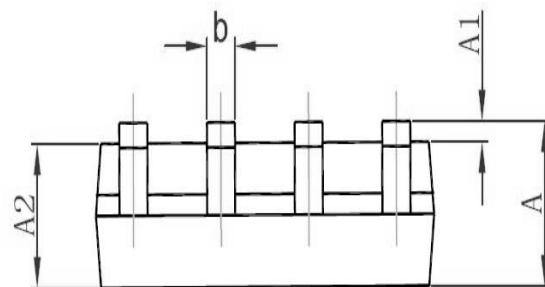
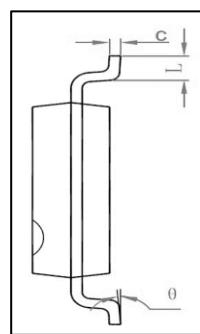
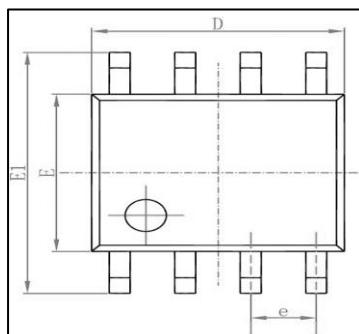
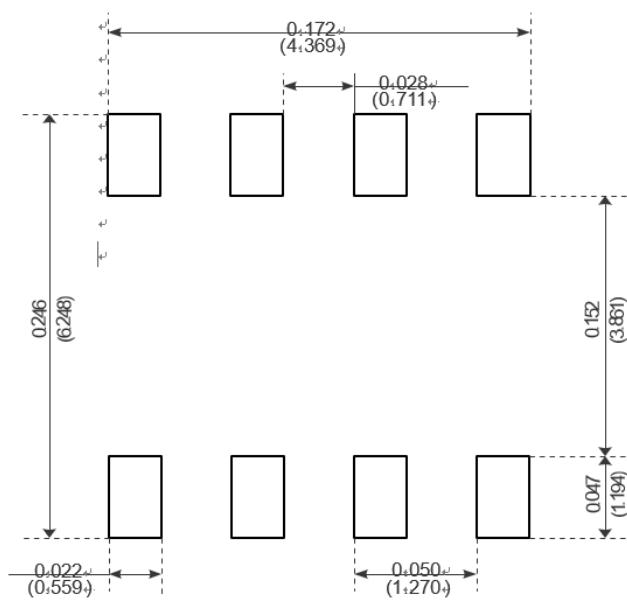


Figure 11. Normalized Maximum Transient Thermal Impedance

**-30V P-Channel Enhancement Mode MOSFET**
**Package Mechanical Data-SOP-8L**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°


**Recommended Minimum Pads**